ISO9001:2000 Certified SCI Quality System

Sierra Components, Inc.

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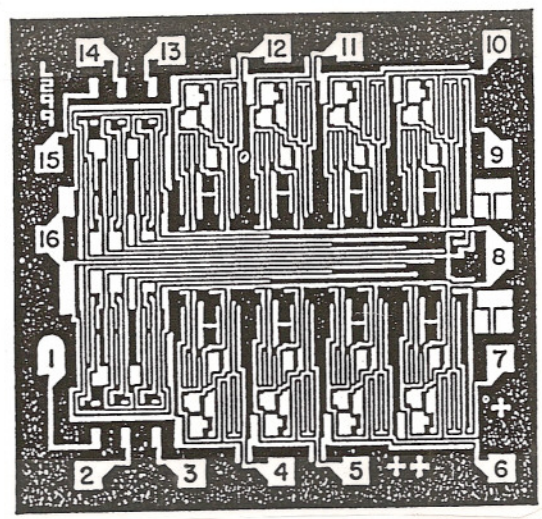
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	E	9	Q3
2	A	10	Q2
3	B	11	Q1
4	Q0	12	Q0
5	Q1	13	B
6	Q2	14	A
7	Q3	15	E
8	VSS	16	VDD

Topside Metal: Al
Backside: Si
Backside Potential: VDD
Mask Ref: 6627
Bond Pads (Mils): 2S

APPROVED BY: **DIE SIZE (Mils): 83 X 79 X 20** **DATE: 3/13/00**
MFG: Harris **THICKNESS:** **P/N: CD4555B**

DG 10.1.2
Rev A 3-4-99